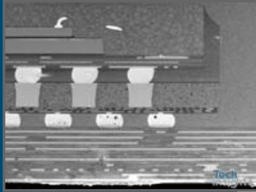
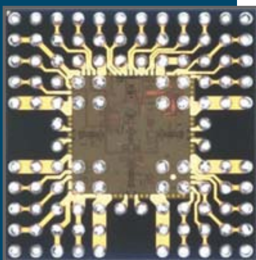
# Advanced Packaging Update:

*Market and Technology Trends*

*Vol. 3-1118*





The third volume of the Advanced Packaging Update presents the current state of outsourced semiconductor assembly and test (OSAT) financials. The latest developments in large-area panel fan-out wafer level package (FO-WLP) trends are presented. An analysis of large area panel FO demand is provided and panel capacity is described. The growing applications for wearable electronics, including smart watches and AR/VR, are discussed along with details of the packages used. Developments in 5G and trends in board-level material are discussed.

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